BFR460L3

Low profile silicon NPN RF bipolar transistor

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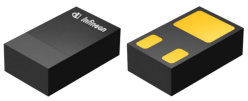
Product description



The BFR460L3 is a low noise device based on a grounded emitter (SIEGET™) that is part of Infineon's established fourth generation RF bipolar transistor family. Its transition frequency f_T of 22 GHz, low current and low voltage characteristics make the device suitable for amplifiers. It remains cost competitive without compromising on ease of use.

Feature list

- Minimum noise figure NF_{min} = 1.1 dB at 1.8 GHz, 3 V, 5 mA
- High gain G_{ms} = 16 dB at 1.8 GHz, 3 V, 20 mA
- OIP_3 = 27 dBm at 1.8 GHz, 3 V, 20 mA
- High ESD performance, typical value 1.5 kV (HBM)

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

- Amplifier for remote keyless entry (RKE)
- Broadband low noise amplifiers (LNAs) for CATV, DVB-T, DAB/DMB and FM/AM radio
- LNAs for sub-1 GHz ISM band applications

Device information

Table 1 Part information

Product name / Ordering code	Package	Pin configuration			Marking	Pieces / Reel
BFR460L3 / BFR460L3E6327XTMA1	TSLP-3-1	1 = B	2 = E	3 = C	AB	15000

Attention*: *ESD (Electrostatic discharge) sensitive device, observe handling precautions

Table of contents

1 Absolute maximum ratings

Table 2 Absolute maximum ratings at T_A = 25 °C (unless otherwise specified)

Parameter	Symbol	Values		Unit	Note or test condition
		Min.	Max.		
Collector emitter voltage	V_{CEO}	–	4.5	V	Open base
			4.2		T_A = -55 °C, open base
Collector emitter voltage	V_{CES}		15		E-B short circuited
Collector base voltage	V_{CBO}		15		Open emitter
Emitter base voltage	V_{EBO}		1.5		Open collector
Base current	I_B		5	mA	–
Collector current	I_C		50		
Total power dissipation [1)]	P_{tot}		200	mW	$T_S \leq$ 108 °C
Junction temperature	T_J		150	°C	
Storage temperature	T_{Stg}	-55			

Attention**: **Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit.

1 T_S is the soldering point temperature. T_S is measured on the emitter lead at the soldering point of the PCB.

2 Thermal characteristics

Table 3 Thermal resistance

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Junction - soldering point	R_{thJS}	–	210	–	K/W	–

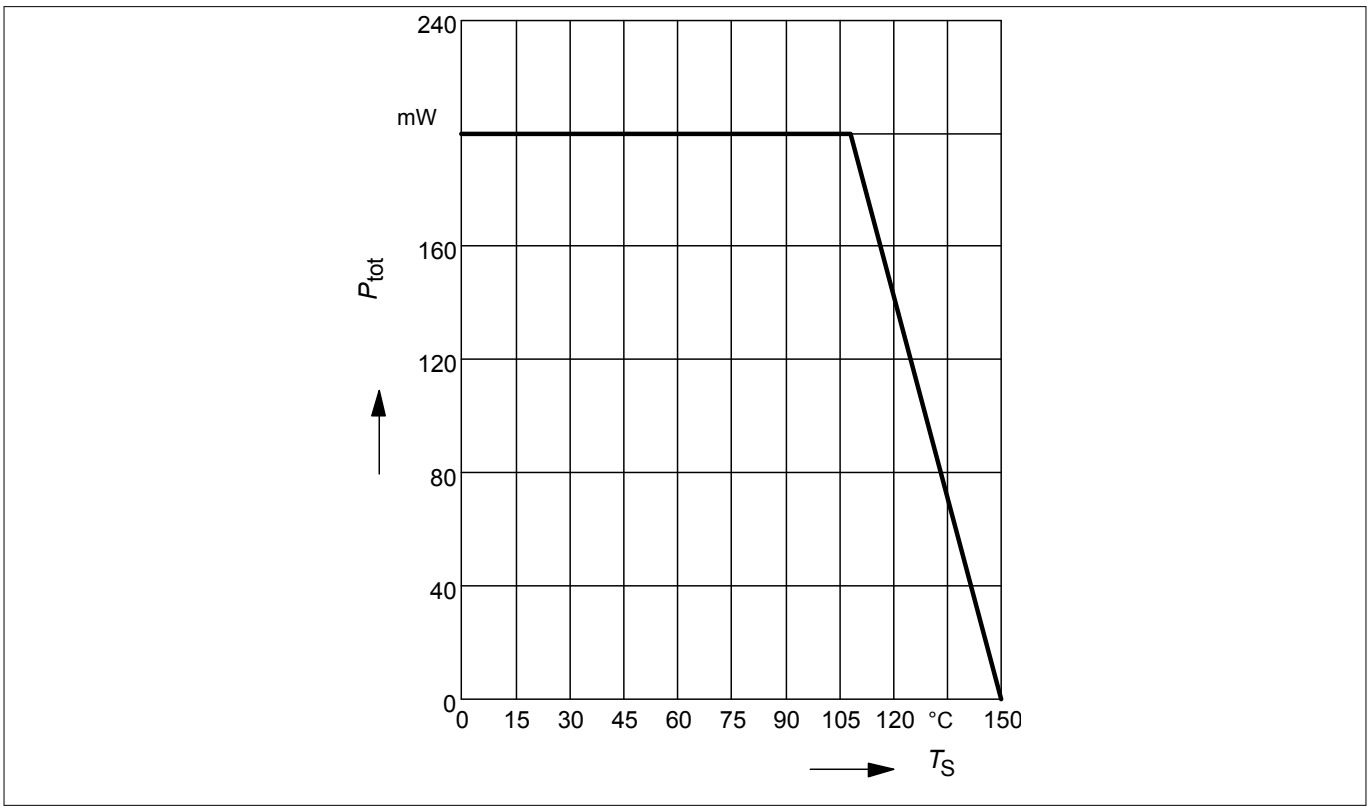


Figure 1 Total power dissipation $P_{tot} = f(T_s)$

3 Electrical characteristics

3.1 DC characteristics

Table 4 DC characteristics at T_A = 25°C

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Collector emitter breakdown voltage	$V_{(BR)CEO}$	4.5	5.8	–	V	I_C = 1 mA, I_B = 0, open base
Collector emitter leakage current	I_{CES}	–	–	10 [2)]	µA	V_{CE} = 15 V, V_{BE} = 0, E-B short circuited
Collector base leakage current	I_{CBO}			100 [2)]	nA	V_{CB} = 5 V, I_E = 0, open emitter
Emitter base leakage current	I_{EBO}			1 [2)]	µA	V_{EB} = 0.5 V, I_C = 0, open collector
DC current gain	h_{FE}	90	120	160		V_{CE} = 3 V, I_C = 20 mA, pulse measured

3.2 General AC characteristics

Table 5 General AC characteristics at T_A = 25°C

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Transition frequency	f_T	16	22	–	GHz	V_{CE} = 3 V, I_C = 30 mA, f = 1 GHz
Collector base capacitance	C_{CB}	–	0.28	0.45	pF	V_{CB} = 3 V, V_{BE} = 0, f = 1 MHz, emitter grounded
Collector emitter capacitance	C_{CE}		0.14	–		V_{CE} = 3 V, V_{BE} = 0, f = 1 MHz, base grounded
Emitter base capacitance	C_{EB}		0.55			V_{EB} = 0.5 V, V_{CB} = 0, f = 1 MHz, collector grounded

2 Maximum values not limited by the device but by the short cycle time of the 100% test.

3.3 Frequency dependent AC characteristics

Measurement setup is a test fixture with Bias T's in a 50 Ω system, T_A = 25 °C.

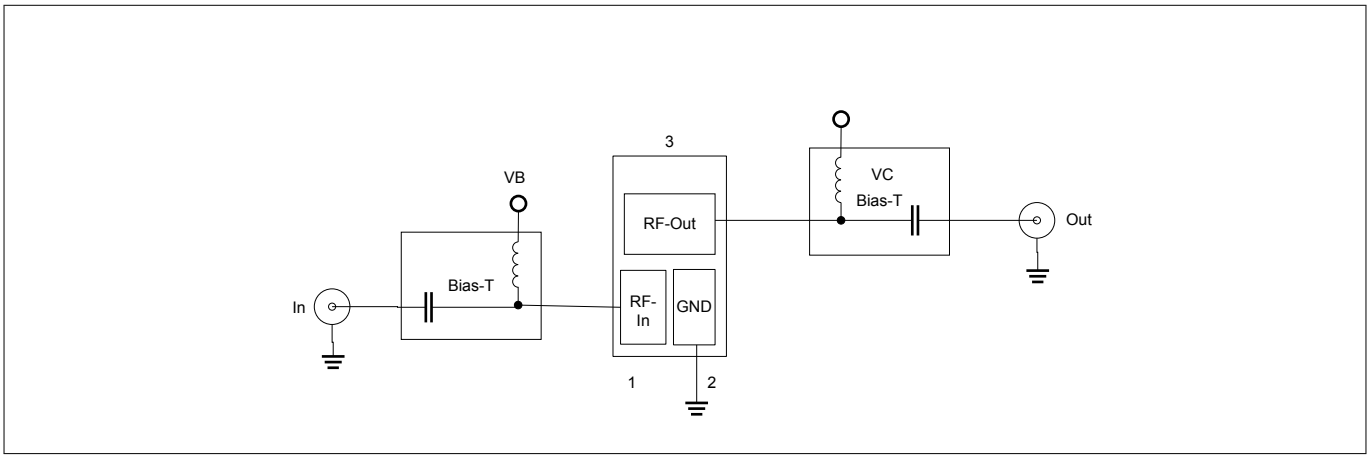


Figure 2 Testing circuit

Table 6 AC characteristics, V_{CE} = 3 V, f = 1.8 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain		–		–	dB	
• Maximum power gain	G_{ms}		16			I_C = 20 mA
• Transducer gain	$\|S_{21}\|^2$		14			
Noise figure						
• Minimum noise figure	NF_{min}		1.1			I_C = 5 mA
Linearity					dBm	
• 3rd order intercept point at output	OIP_3		27			$Z_S = Z_L$ = 50 Ω, I_C = 20 mA
• 1 dB compression point at output	OP_{1dB}		11.5			

Table 7 AC characteristics, V_{CE} = 3 V, f = 3 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain		–		–	dB	
• Maximum power gain	G_{ma}		11			I_C = 20 mA
• Transducer gain	$\|S_{21}\|^2$		10			
Noise figure						
• Minimum noise figure	NF_{min}		1.35			I_C = 5 mA

Note: $G_{ms} = IS_{21} / S_{12}I$ for $k < 1$; $G_{ma} = IS_{21} / S_{12}\, I(k-(k^2-1)^{1/2})$ for $k > 1$. In order to get the NF_{min} values stated in this chapter, the test fixture losses have been subtracted from all measured results. OIP_3 value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50 Ω from 0.2 MHz to 12 GHz.

3.4 Characteristic AC diagrams

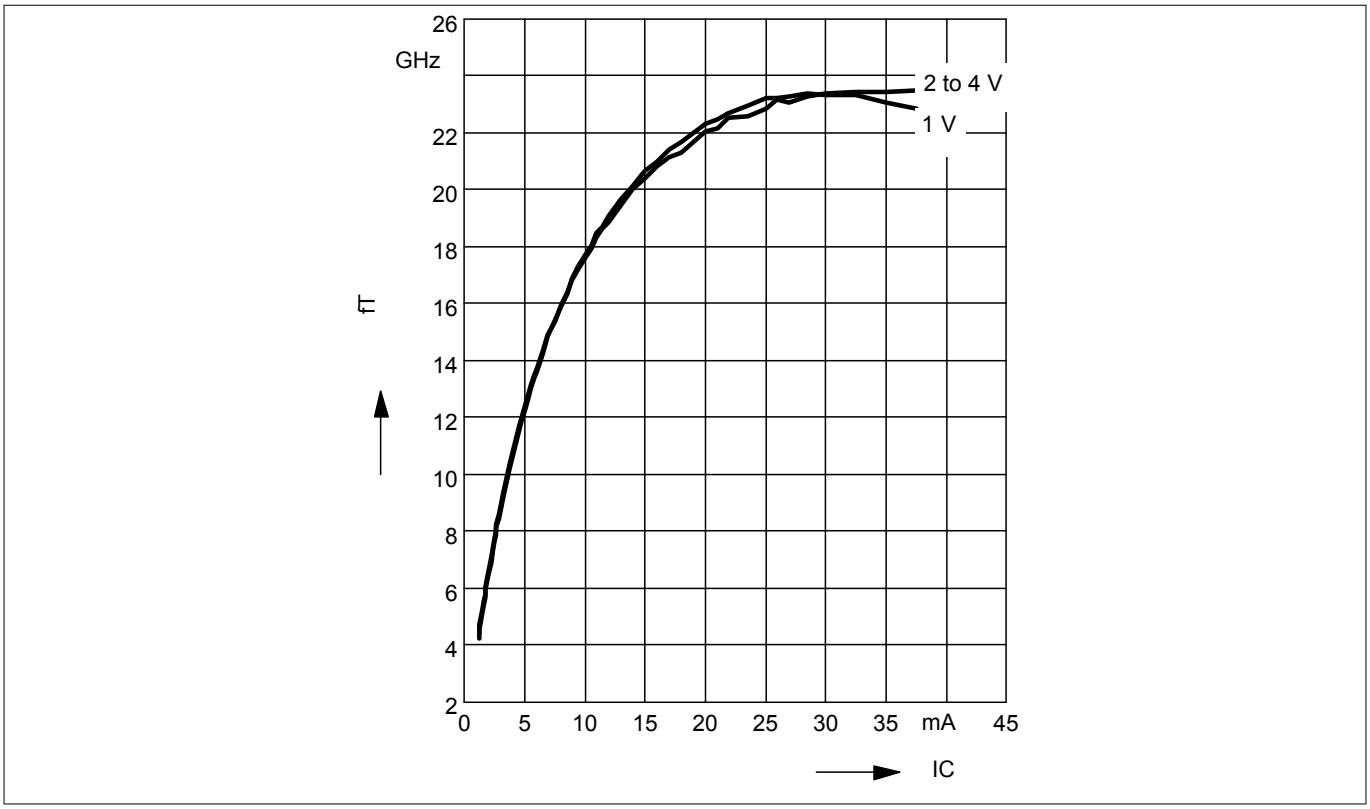


Figure 3 **Transition frequency f_T = f(I_C), f = 1 GHz, V_{CE} = parameter**

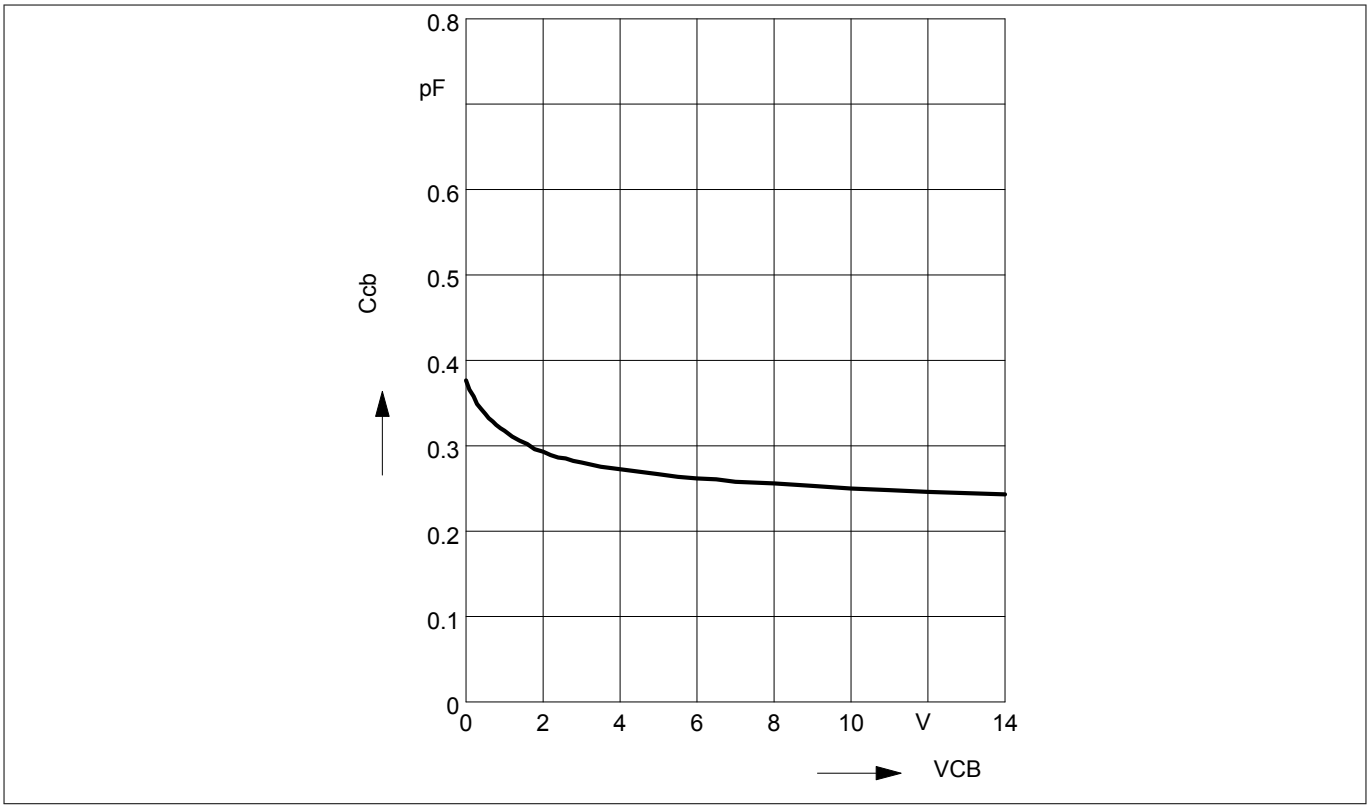


Figure 4 **Collector base capacitance C_{CB} = f(V_{CB}), f = 1 MHz**

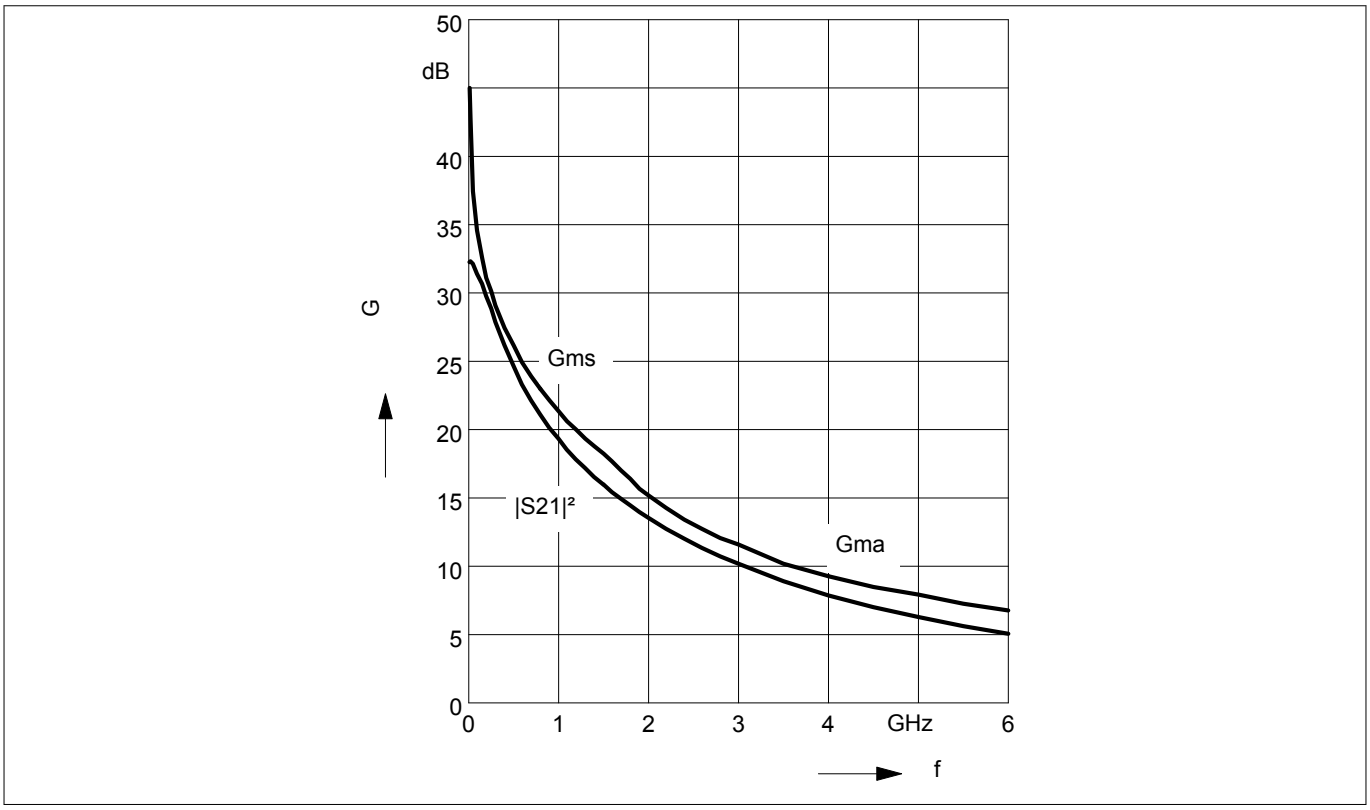


Figure 5 **Gain G_{ma}, G_{ms}, $|S_{21}|^2$ = f(f), V_{CE} = 3 V, I_C = 20 mA**

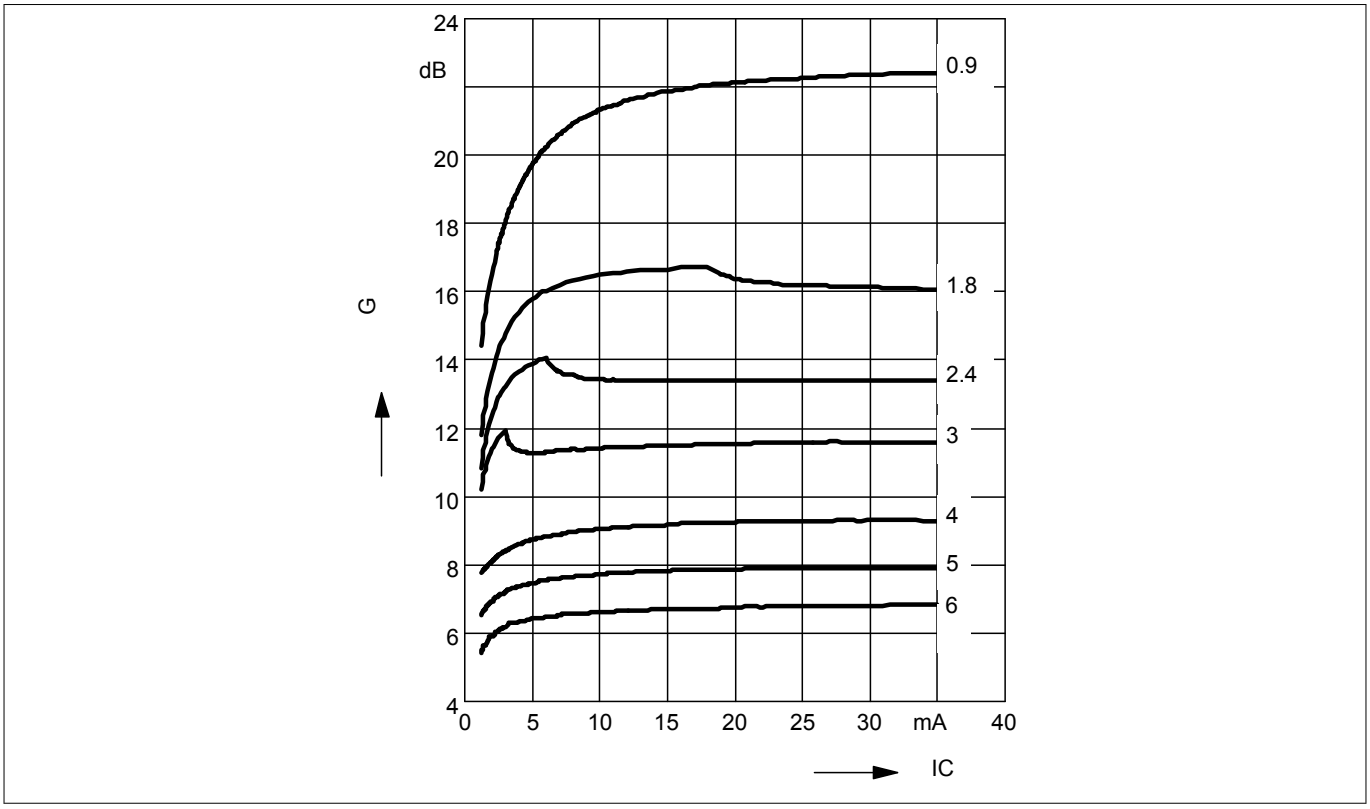


Figure 6 **Maximum power gain G_{max} = f(I_C), V_{CE} = 3 V, f = parameter in GHz**

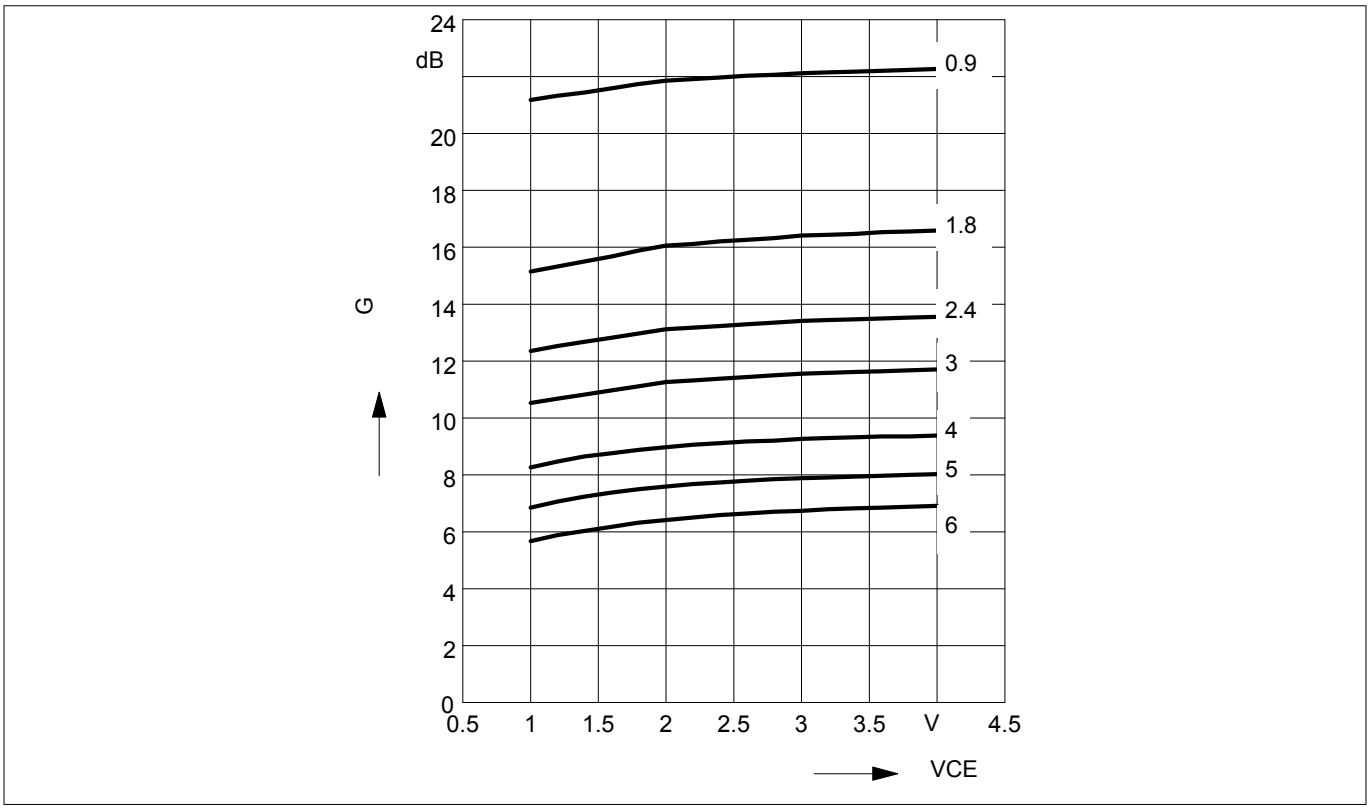


Figure 7 Maximum power gain G_{max} = f(V_{CE}), I_C = 20 mA, f = parameter in GHz

Note: The curves shown in this chapter have been generated using typical devices but shall not be considered as a guarantee that all devices have identical characteristic curves. T_A = 25 °C.

4 Package information TSLP-3-1

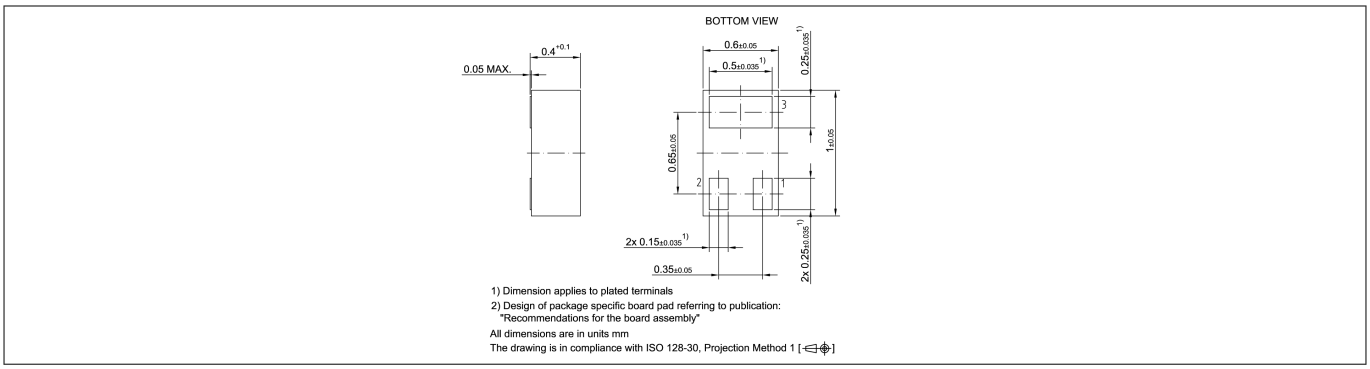


Figure 8 Package outline

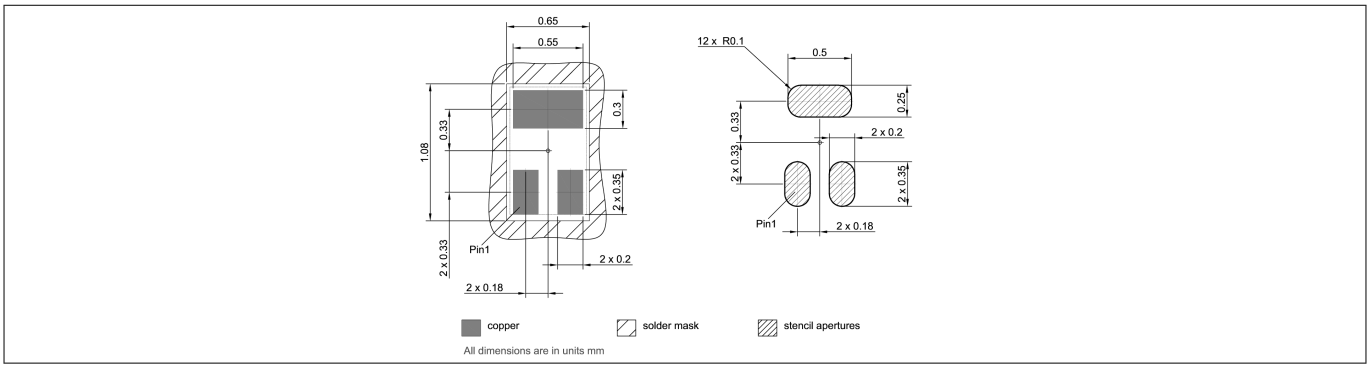


Figure 9 Foot print

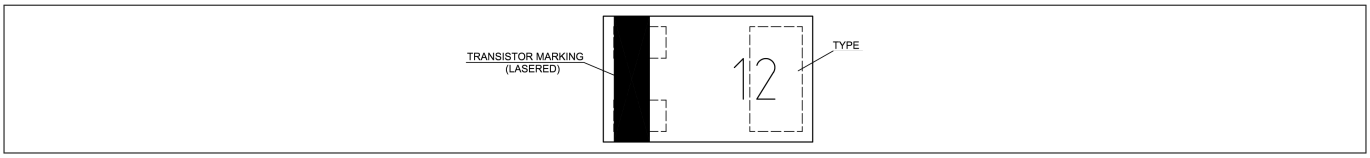


Figure 10 Marking layout example

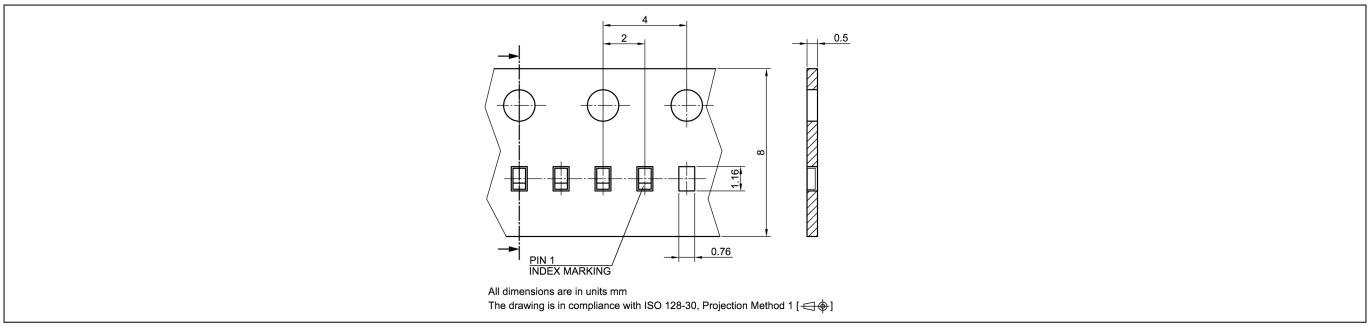


Figure 11 Tape information

*Note: See our **Recommendations for Printed Circuit Board Assembly of TSLP/TSSLP/TSNP Packages** .*
The marking layout is an example. For the real marking code refer to the device information on the first page. The number of characters shown in the layout example is not necessarily the real one. The marking layout can consist of less characters.

Revision history

Document version	Date of release	Description of changes
Revision 2.0	2019-01-25	New datasheet layout.

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